L Number	Hits	Search Text	DB	Time stamp
1	4277	(438/\$.ccls.) and (bond\$3 solder\$3) same	USPAT	2004/07/19 16:17
		(IC chip\$1 die\$1 dice) near15 (substrate\$1	1	
		carrier board pcb)		
2	1747	((438/\$.ccls.) and (bond\$3 solder\$3) same	USPAT	2004/07/19 16:18
		(IC chip\$1 die\$1 dice) near15 (substrate\$1		
		carrier board pcb)) and bond\$3 same	•	
	İ	solder\$3 same (IC chip\$1 die\$1 dice)		
		near15 (substrate\$1 carrier board pcb)		
3	0	(((438/\$.ccls.) and (bond\$3 solder\$3) same	USPAT	2004/07/19 16:20
1		(IC chip\$1 die\$1 dice) near15 (substrate\$1		
		carrier board pcb)) and bond\$3 same		
		solder\$3 same (IC chip\$1 die\$1 dice)		
		near15 (substrate\$1 carrier board pcb))		
		and solder\$3 near7 (IC chip\$1 die\$1 dice)		
		same "or" same solder\$3 near7 (substrate\$1		
		carrier board pcb)		
4	1155	, , , , , , , , , , , , , , , , , , ,	USPAT	2004/07/19 16:22
		(IC chip\$1 die\$1 dice) near15 (substrate\$1		;
		carrier board pcb)) and bond\$3 same		
		solder\$3 same (IC chip\$1 die\$1 dice)		
		near15 (substrate\$1 carrier board pcb))	ı	
		and solder\$3 near7 (IC chip\$1 die\$1 dice	1	
1		device\$1) same solder\$3 near7		
_	0.47	(substrate\$1 carrier board pcb)	HCDAM	2004/07/10 16:26
5	947	((((438/\$.ccls.) and (bond\$3 solder\$3)	USPAT	2004/07/19 16:26
		same (IC chip\$1 die\$1 dice) near15		•
		(substrate\$1 carrier board pcb)) and bond\$3 same solder\$3 same (IC chip\$1 die\$1		
		dice) near15 (substrate\$1 carrier board		
		pcb)) and solder\$3 near7 (IC chip\$1 die\$1		
		dice device\$1) same solder\$3 near7		
		(substrate\$1 carrier board pcb)) and		
		(bond\$3 weld\$3 join\$3) near10 (IC chip\$1	1	
		die\$1 dice device\$1) near3 (substrate\$1		
		carrier board pcb)		
6	159	· ·	USPAT	2004/07/19 16:29
		same (IC chip\$1 die\$1 dice) near15		
	1	(substrate\$1 carrier board pcb)) and		
	1	bond\$3 same solder\$3 same (IC chip\$1 die\$1		
		dice) near15 (substrate\$1 carrier board		
		pcb)) and solder\$3 near7 (IC chip\$1 die\$1		
		dice device\$1) same solder\$3 near7		
		(substrate\$1 carrier board pcb)) and		
		(bond\$3 weld\$3 join\$3) near10 (IC chip\$1		
		die\$1 dice device\$1) near3 (substrate\$1		
		carrier board pcb)) and (deposit\$4		
		application appli\$2 applying) near3		
		(solder\$3 braz\$3) near10 (IC chip\$1 die\$1		
		dice device\$1) and (deposit\$4 application		
1		appli\$2 applying) near3 (substrate\$1		
		carrier board pcb)		